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YEO et al.(10) **Pub. No.: US 2022/0377889 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **PRINTED CIRCUIT BOARD AND
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ABSTRACT

A printed circuit board (PCB) (4) including an upper surface having one or more electrical terminals (9) thereon, said terminal adapted for connection to corresponding terminal of one or more electrical components, and further including one or more platforms (10) fabricated thereon, said platforms being located adjacent to corresponding component terminals, said platforms being adapted to support an electrical component thereupon, such that a portion of the component overhangs said platform above said corresponding PCB terminal.

